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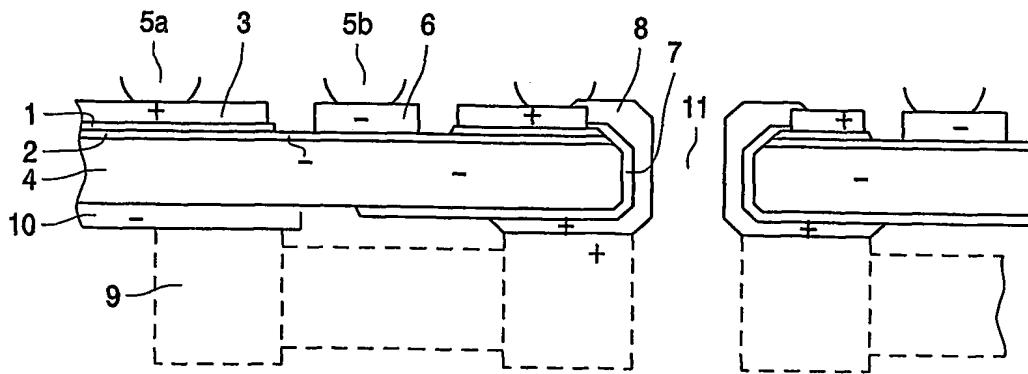
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(54) Title: ELECTRONIC PACKAGING STRUCTURE WITH INTEGRATED DISTRIBUTED DECOUPLING CAPACITORS



(57) Abstract: An electronic packaging structure, comprising a substrate; a first electrode layer on a first side of said substrate; dielectric material arranged in a preselected pattern on said first electrode layer; and a second electrode layer forming a plurality of second electrodes which are arranged on said preselected pattern of dielectric material to form a distributed capacitive structure together with said first electrode layer, is characterized in that a second decoupling capacitor stage is arranged on a second side of said substrate opposite said first side and is electrically connected to said distributed capacitive structure, said second decoupling stage having a capacity higher than that of said distributed capacitive structure.



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